



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-28
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VNH7100BASTR	UCQ7*VH76AAX	A	Z7GA	2018-09-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	150.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	3.9x9.9x1.375	16	flat	
Comment	Package: SO 16 .15 TO JEDEC MS-012			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.53	Die - Leadframe	3553

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	UCQ7*VH76AAX					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	4.597	mg	supplier	die	Silicon (Si)	7440-21-3		4.285	mg	932130	28567
				supplier	metallization	Aluminium (Al)	7429-90-5		0.082	mg	17838	547
				supplier	metallization	Copper (Cu)	7440-50-8		0.030	mg	6526	200
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1305	40
				supplier	metallization	Tungsten (W)	7440-33-7		0.059	mg	12834	393
				supplier	Passivation	Silicon Oxide	7631-86-9		0.047	mg	10224	313
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	436	15
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1305	40
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	5438	167
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	435	13
Leadframe	Copper and its alloy	54.302	mg	Supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.053	mg	11529	353
				Supplier	Alloy	Iron	7439-89-6		1.276	mg	23498	8507
				Supplier	Alloy	Phosphorus	7723-14-0		0.045	mg	829	300
				Supplier	Alloy	Zinc	7440-66-6		0.068	mg	1252	453
				Supplier	Alloy	Copper	7440-50-8		52.360	mg	964237	349067
				Supplier	metallization	Silver	7440-22-4		0.011	mg	203	73
				Supplier	metallization	Nickel	7440-02-0		0.508	mg	9355	3387
				Supplier	metallization	Palladium	7440-05-3		0.014	mg	258	93
				Supplier	metallization	Gold	7440-57-5		0.020	mg	368	133
				Supplier	glue	Silver	7440-22-4		4.097	mg	949919	27313
Die Attach	Other organic materials	4.313	mg	Supplier	glue	High boiling methacrylateProprietary	Proprietary		0.216	mg	50081	1440
				Supplier	wire	Copper	7440-50-8		0.102	mg	1000000	680
Bonding wire	Other inorganic materials	0.102	mg	Supplier	wire	Copper	7440-50-8		0.102	mg	1000000	680
				Supplier	mold compound	Silica fused	60676-86-0		78.884	mg	909997	525893
Encapsulation	Other organic materials	86.686	mg	Supplier	mold compound	Epoxy resin	25068-38-6		4.334	mg	49997	28893
				Supplier	mold compound	Phenol resin A	29690-82-2		1.474	mg	17004	9827
				Supplier	mold compound	Phenol resin B	Proprietary		1.734	mg	20003	11560
				Supplier	mold compound	Carbon black	1333-86-4		0.260	mg	2999	1733